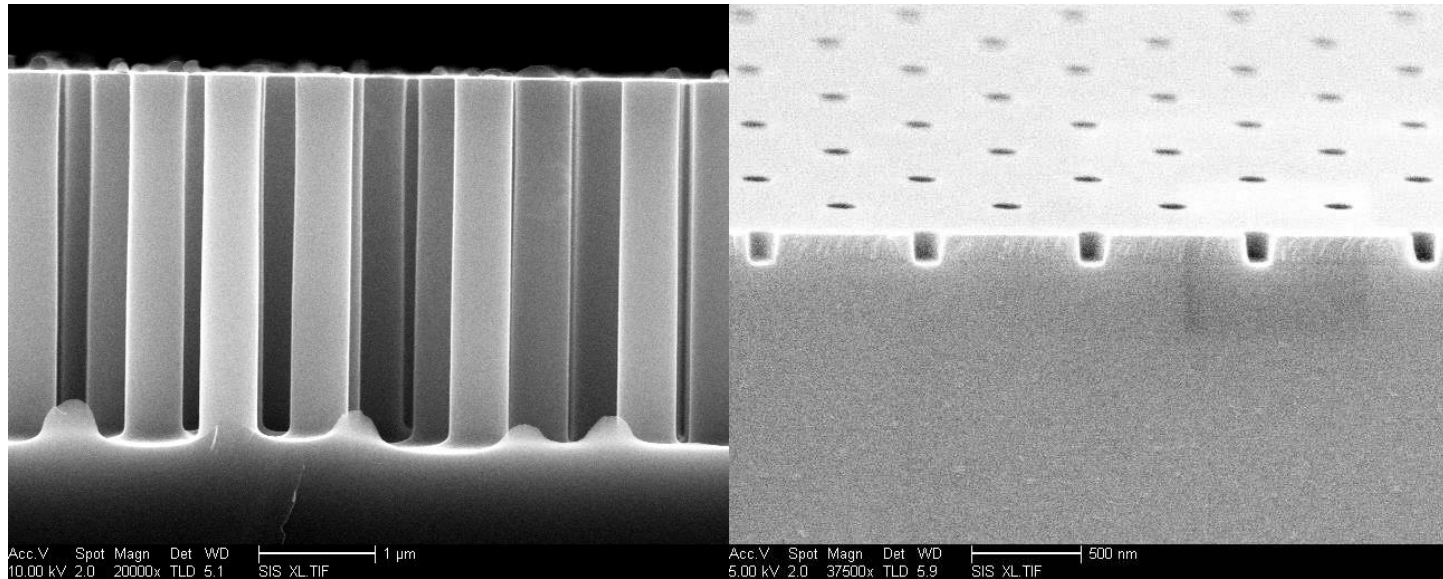


Dry Etch at Nano3/SDNI UC San Diego

2022 NNCI Etch Symposium-University of Pennsylvania, April 21-22

Conor Holzhall, Xuekun Lu



Current Etch Capabilities

RIE/ICP

- Oxford Plasmalab System 100
- PlasmaTherm SLR RIE/ICP
- Trion Minilock Phantom III RIE/ICP
- Oxford Plasmalab 80+

Ashers

- Plasma Etch PE100
- PVA Tepla Plasma System 100

Vapor Etch

- Xactix Xetch
- Idonus HF VPE

Wet Etch

Various Acid/Base Etchants

- Cr, Al, Cu, Mo, Au, SiC, SiO₂, etc.

Oxford Plasmalab System 100



Options or Upgrades

- Cryo mode
- LF for notching control

Gases

CHF₃, C₄F₈, CF₄, Ar, SF₆, O₂

Plasma-Therm SLR RIE/ICP Plasma Etch System

New installation in 2020

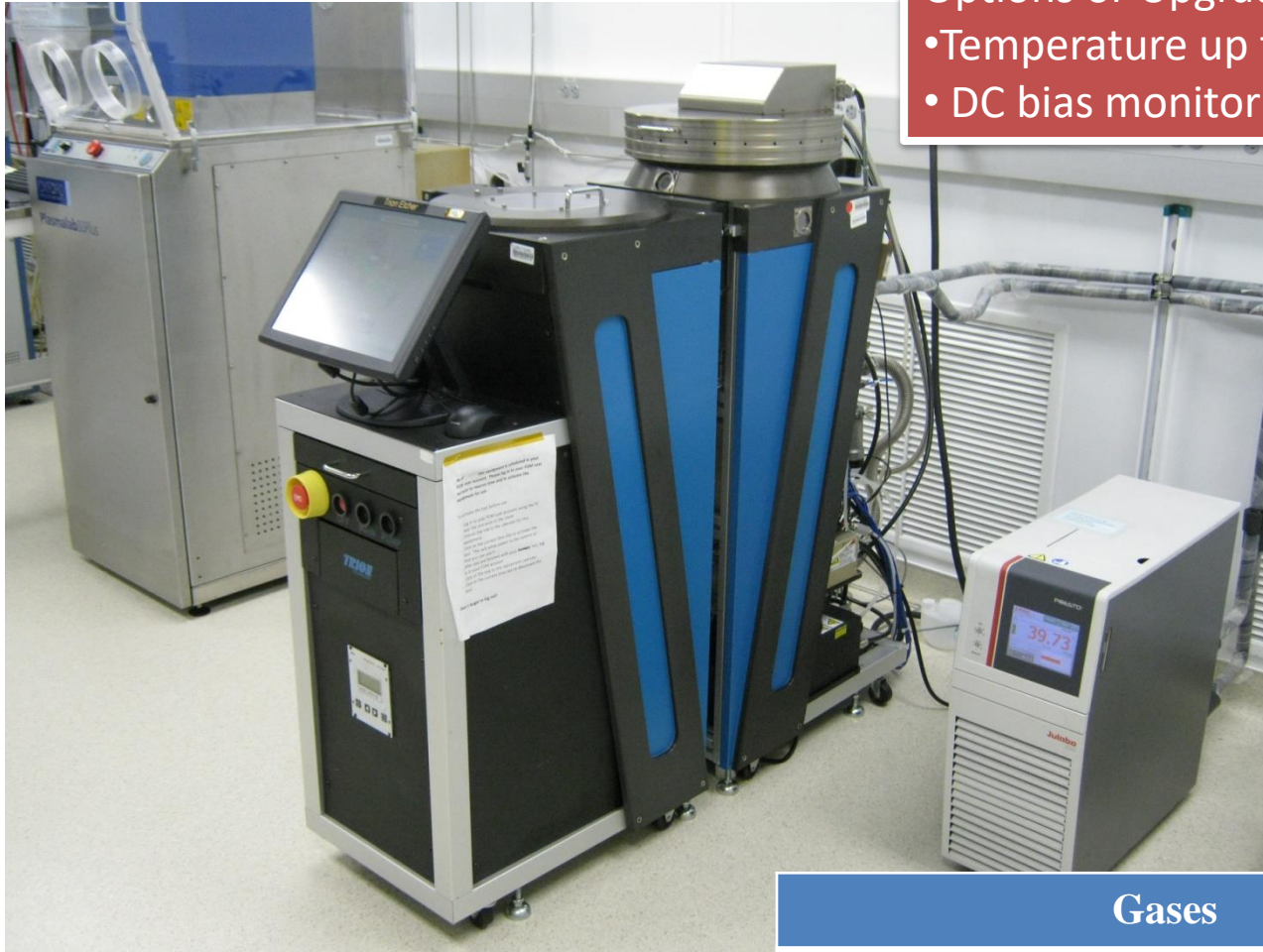


Gases

CHF₃, C₄F₈, CF₄, Ar, SF₆, O₂



Trion Minilock Phantom III ICP



Options or Upgrades

- Temperature up to 150°C
- DC bias monitoring

Gases

SF₆, Cl₂, BCl₃, CF₄, CH₄, O₂, H₂, He, Ar

Oxford Plasmalab 80+



Gases

Cl₂, BCl₃, CHF₃, CF₄, SF₆, O₂, Ar

Plasma Etch PE100



Gases

O₂

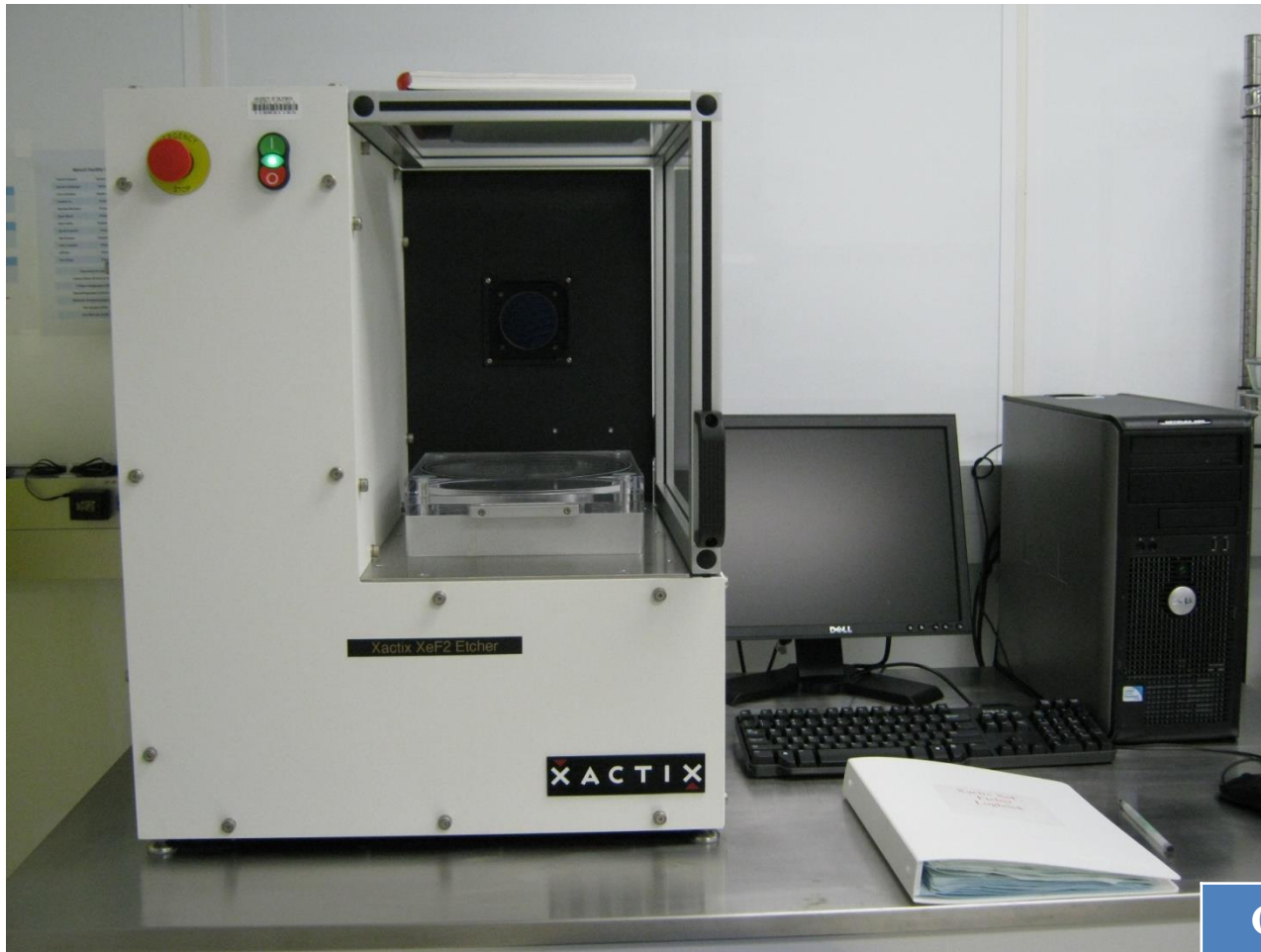
PVA TePla Plasma System 100



Gases

O₂

Xactix Xetch e1 Series



Gases

XeF₂

Idonus HF VPE-150



Gases

HF Vapor

Future plans: Looking to buy a new RIE etcher

P80-type tool (oxide, nitride, metal etching) with load lock



Available tools

Tool	Type	Gases	Applications	Wafer Size
Oxford Plasmalab System 100	ICP	CHF ₃ , C ₄ F ₈ , CF ₄ , Ar, SF ₆ , O ₂	Si, SiO ₂	Up to 150mm
Plasma-Therm SLR RIE/ICP Plasma Etch System (<i>new</i>)	ICP	CHF ₃ , C ₄ F ₈ , CF ₄ , Ar, SF ₆ , O ₂	Si, SiO ₂	Up to 150mm
Trion Minilock Phantom III ICP	ICP	SF ₆ , Cl ₂ , BCl ₃ , CF ₄ , CH ₄ , O ₂ , H ₂ , He, Ar	III-Vs, oxides, polymers, metals	Up to 150mm
Oxford Plasmalab 80+	RIE	Cl ₂ , BCl ₃ , CHF ₃ , CF ₄ , SF ₆ , O ₂ , Ar	Oxides, nitrides, metals	Up to 150mm
Plasma Etch PE100	Asher	O ₂	Resist removal, polymers	Up to 200mm
PVA TePla Plasma System 100	Asher	O ₂	Resists, polymers	Up to 100mm
Xactix Xetch e1 Series	Release	XeF ₂	Release, Si etch	Up to 100mm
Idonus HF VPE-150	Release	HF Vapor	Release, SiO ₂ etch	Up to 150mm